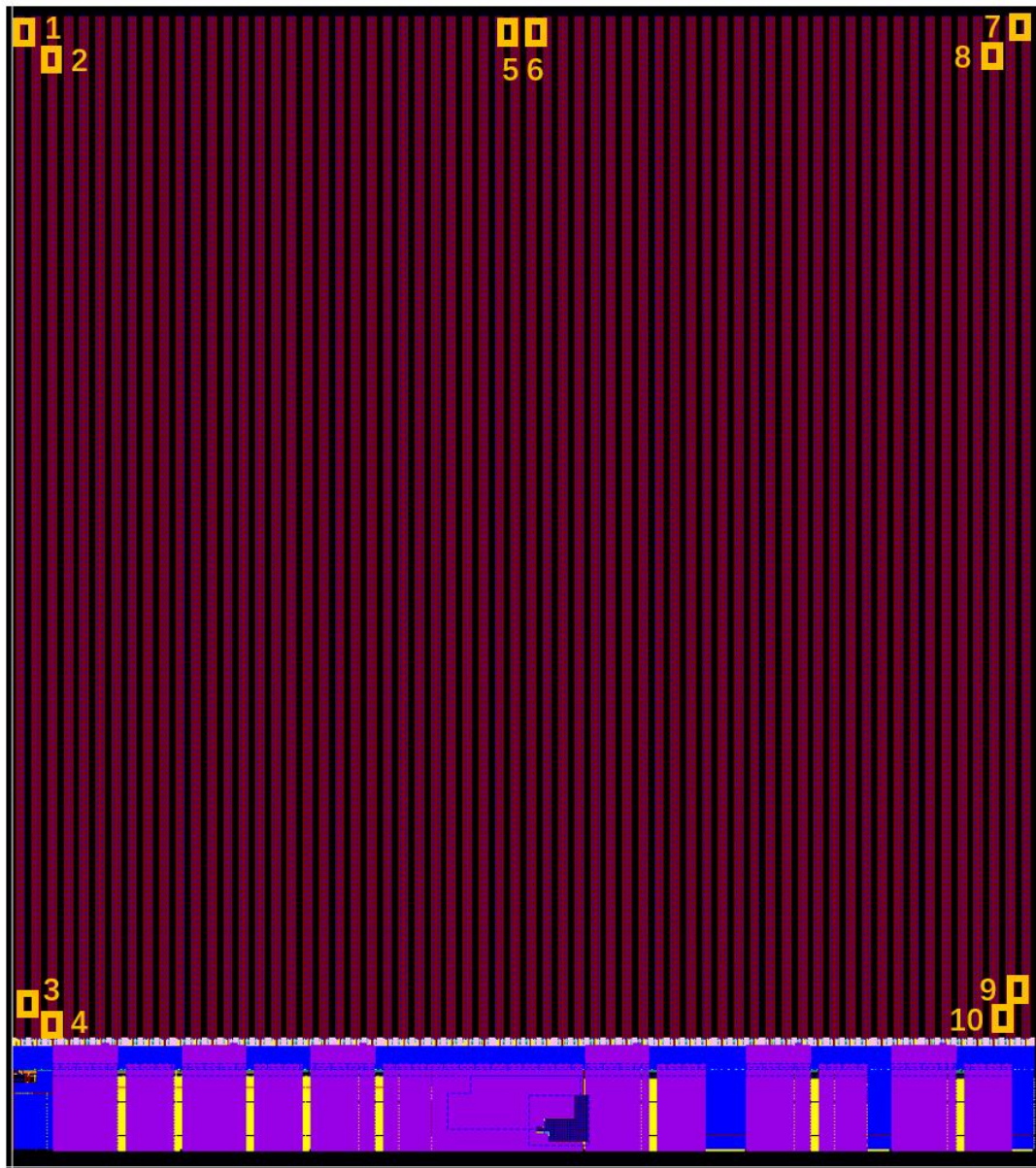


HYLITE100F FIB 说明

HYLITE100F 芯片尺寸约：12673 um × 14272 um。本次 FIB 目的是将指定位置芯片钝化层去除，将顶层金属引出并长 PAD，共 10 处。PAD 尺寸 50um*50um。

下面是 FIB 位置的指示图，以黄色方框指示（芯片 I/O 位于图片下底边）：

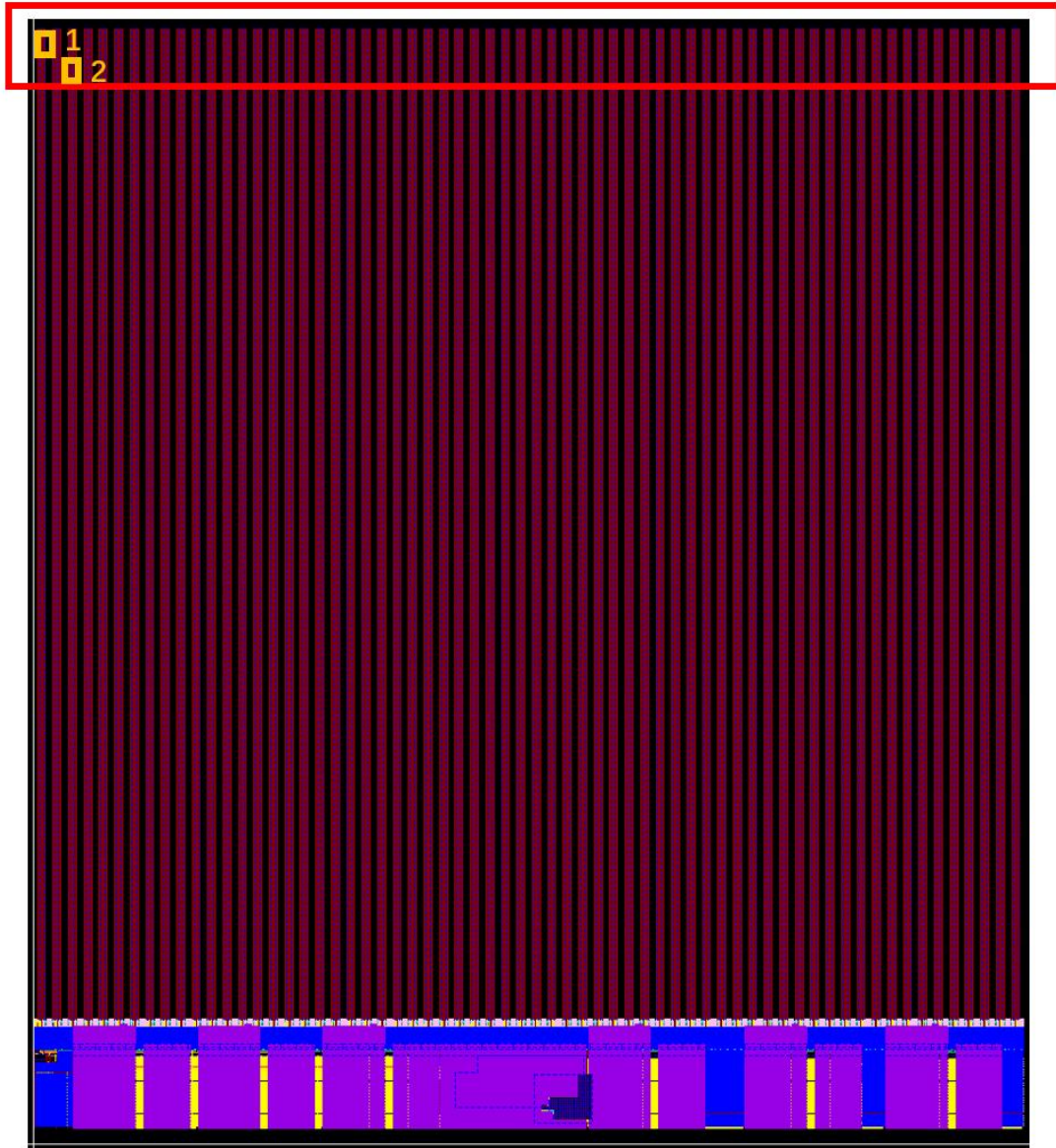


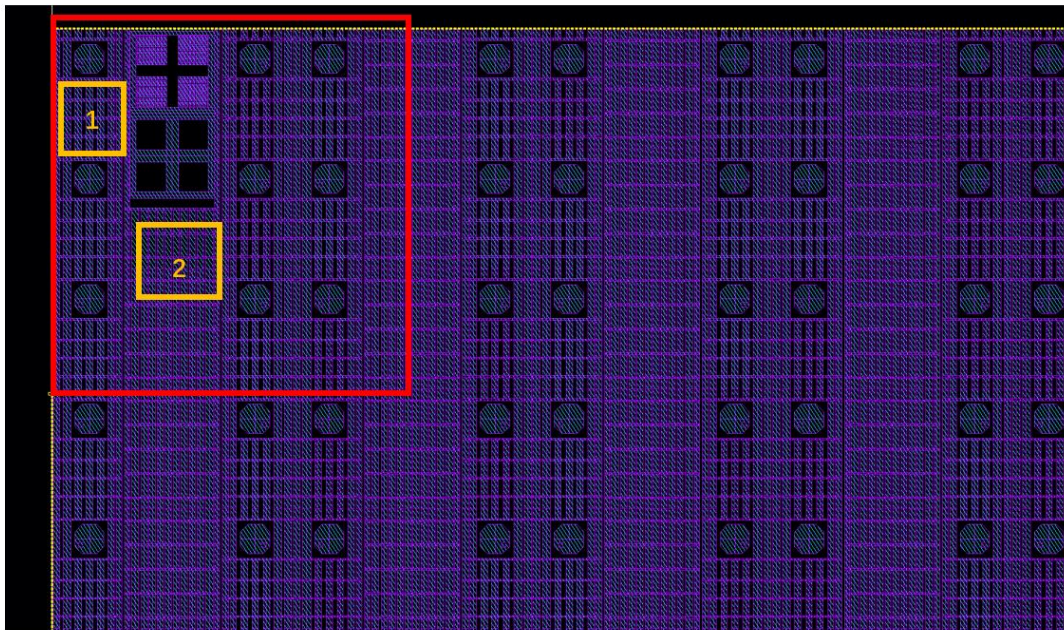
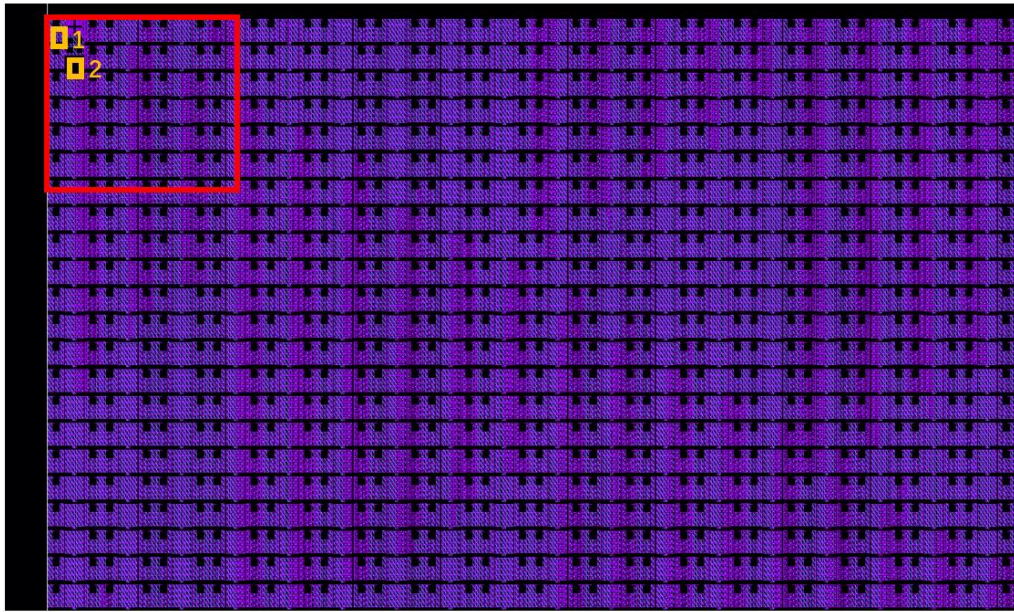
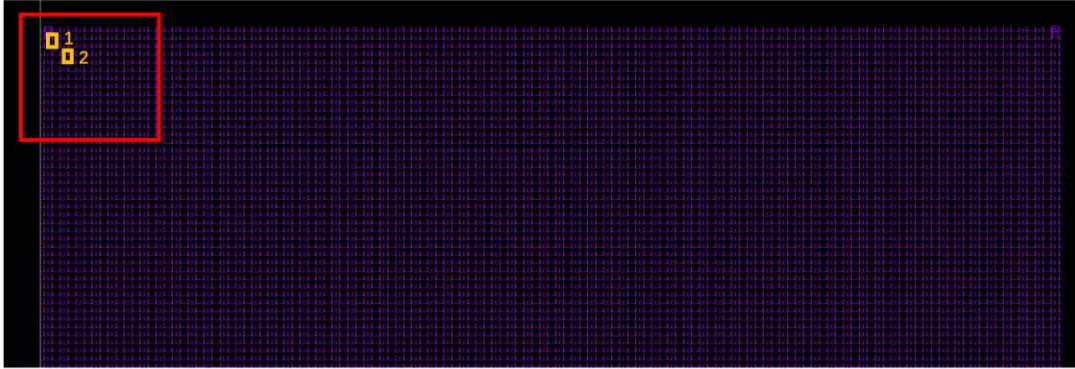
一． 需求：

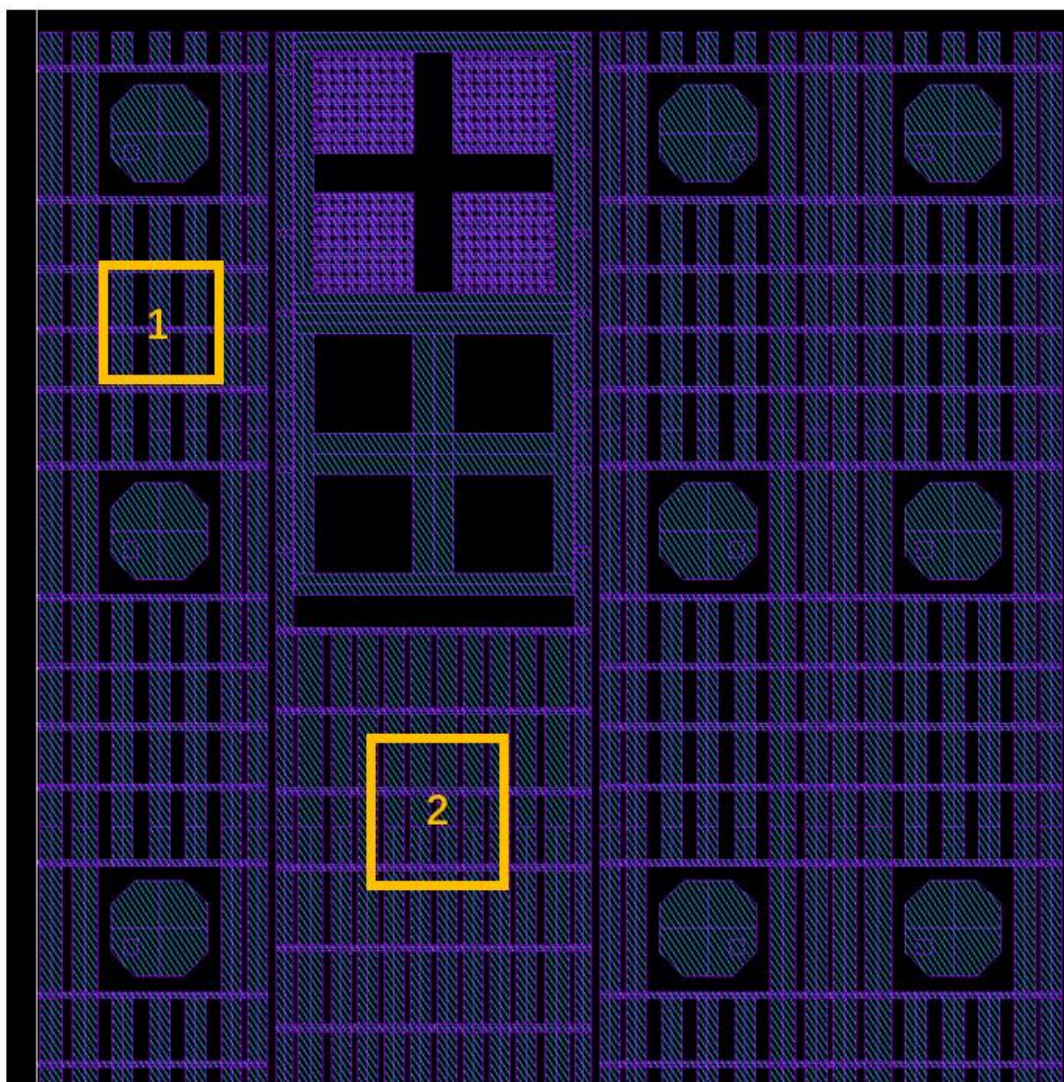
数量：共 FIB 3 片

二． 位置寻找具体的具体流程（红色框为放大区域，黄色框为操作位置）：

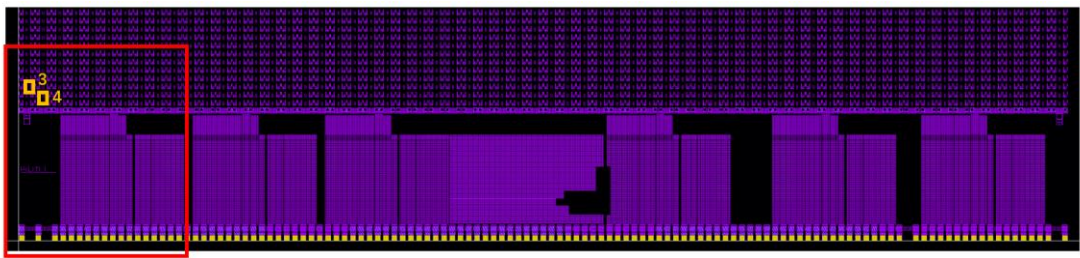
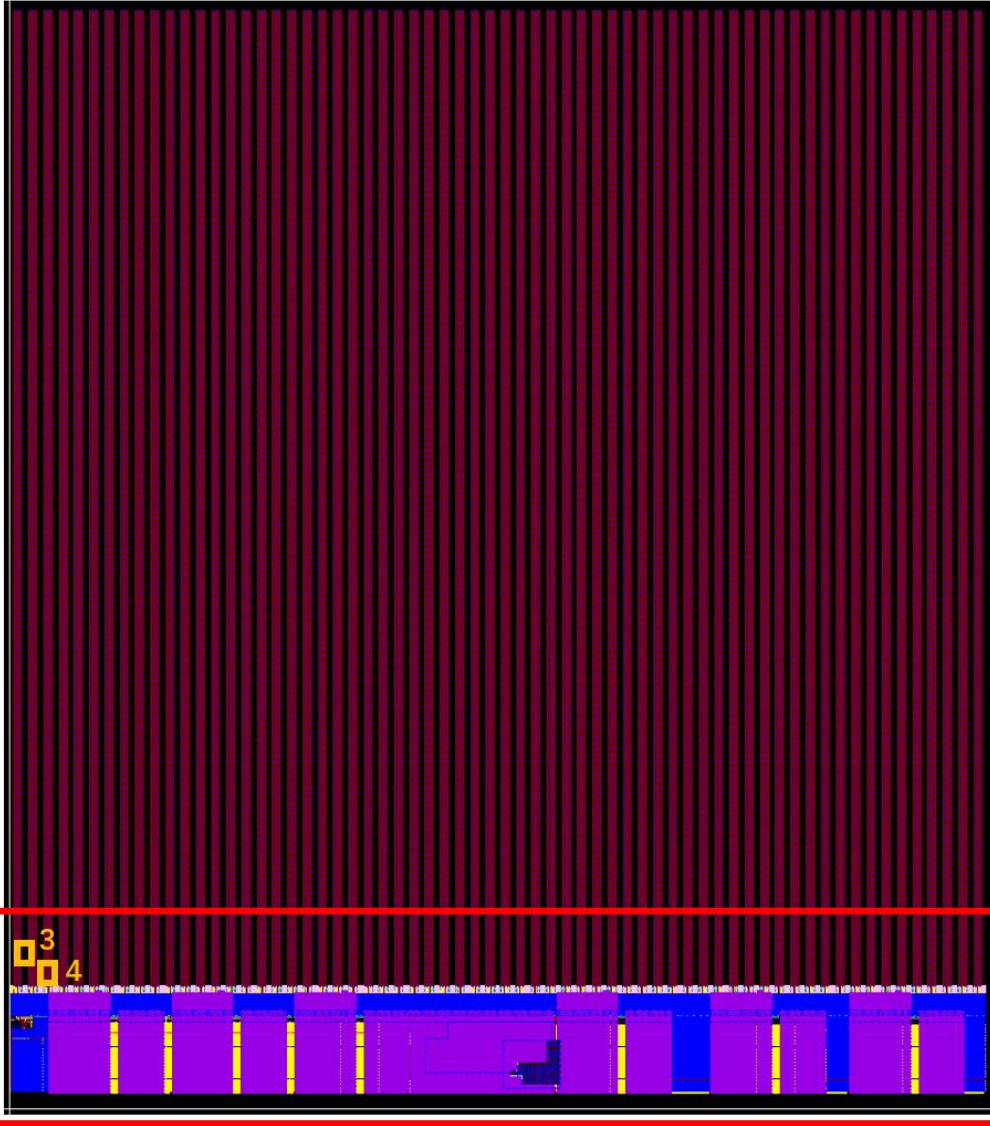
1) 1, 2 号点位

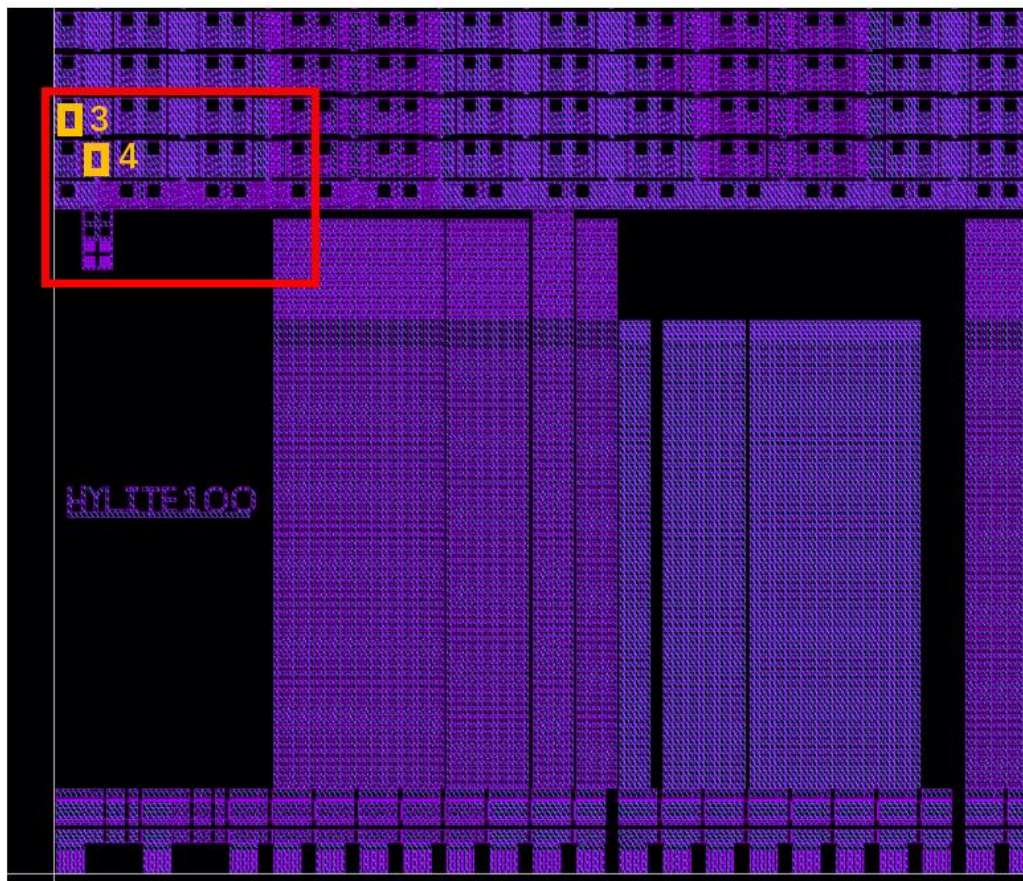


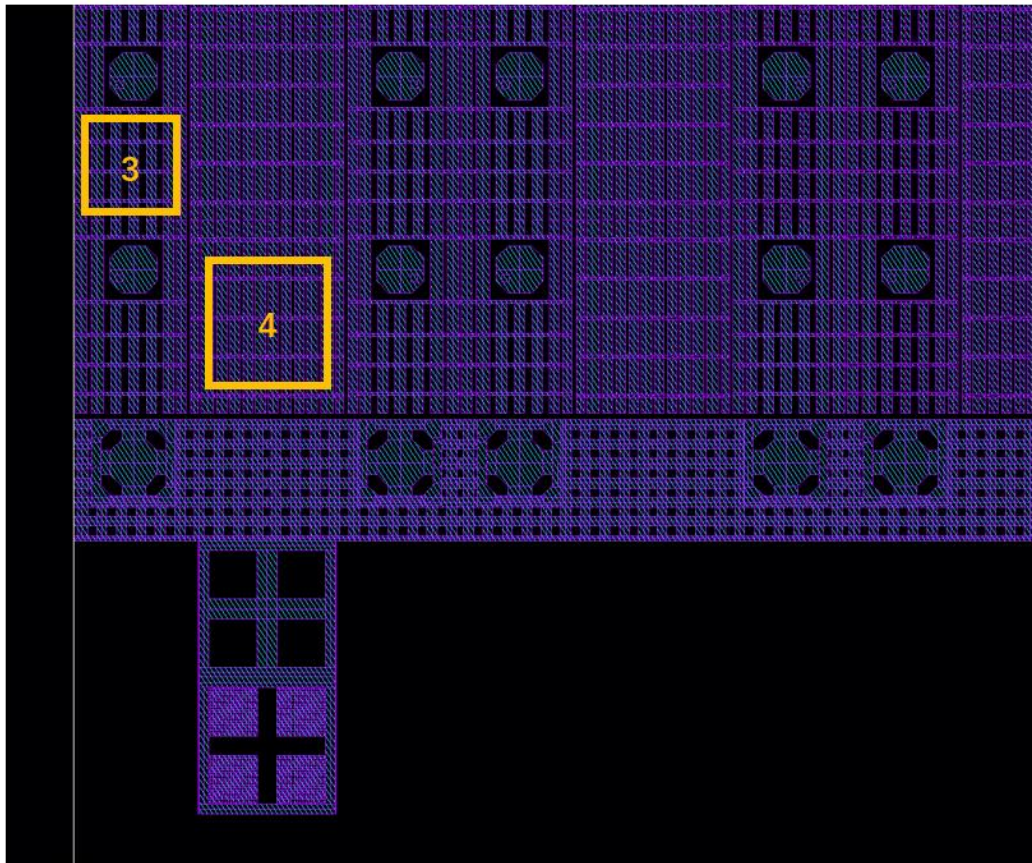




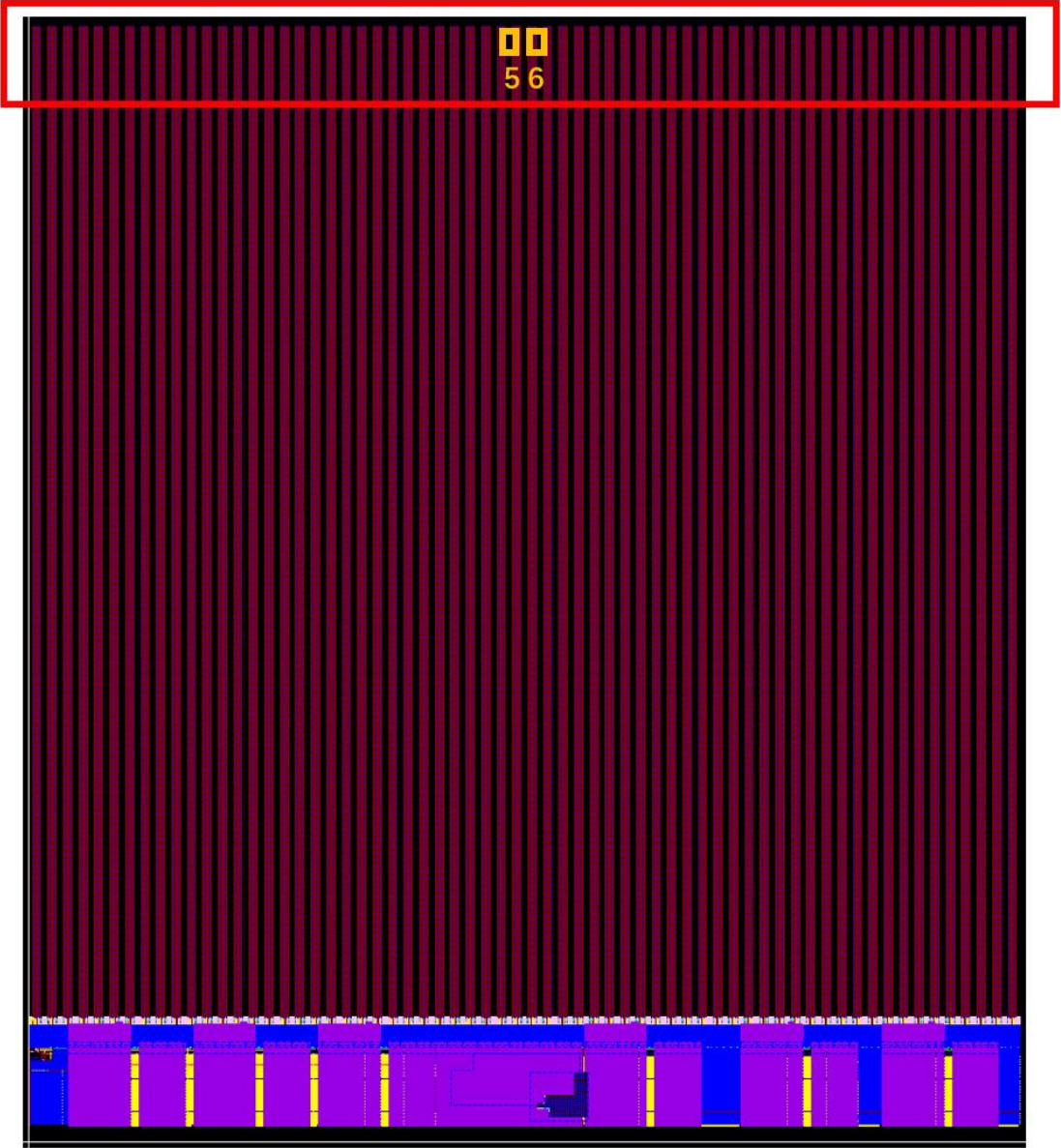
2) 3, 4 号点位

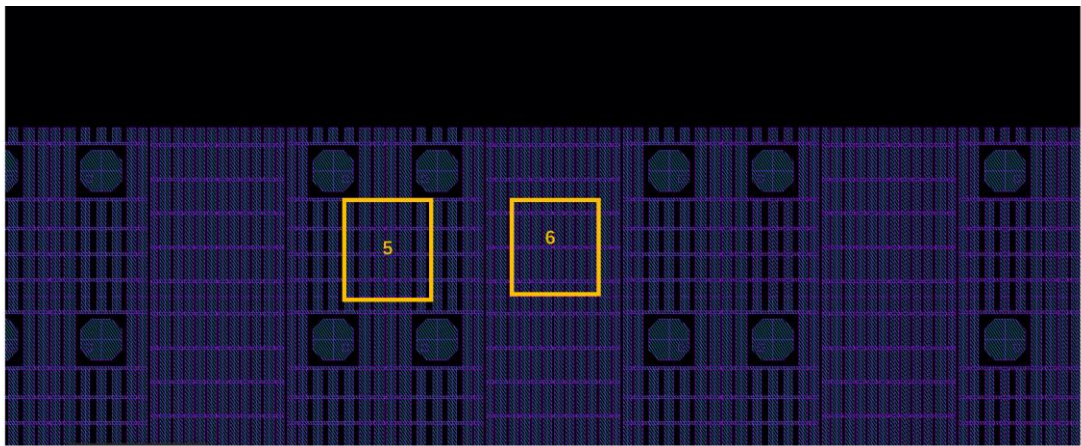
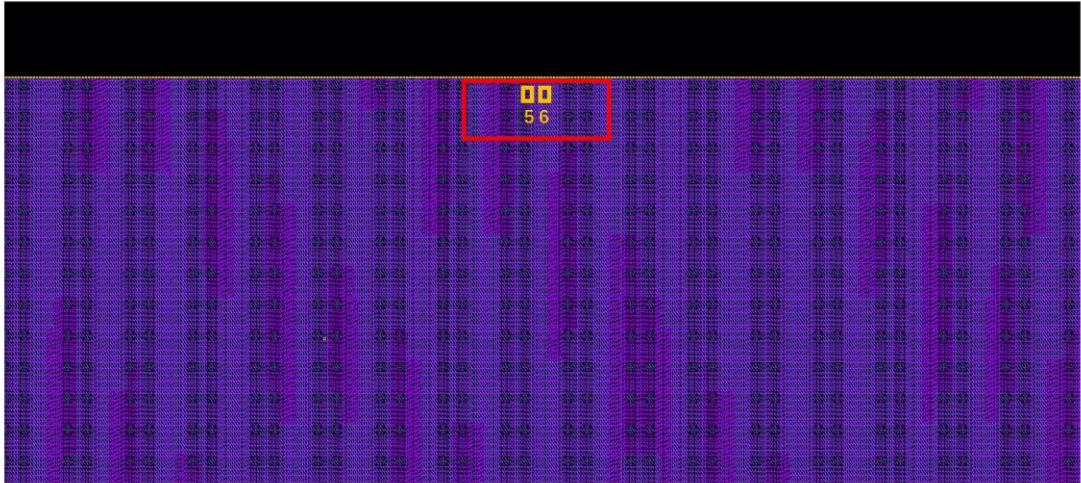




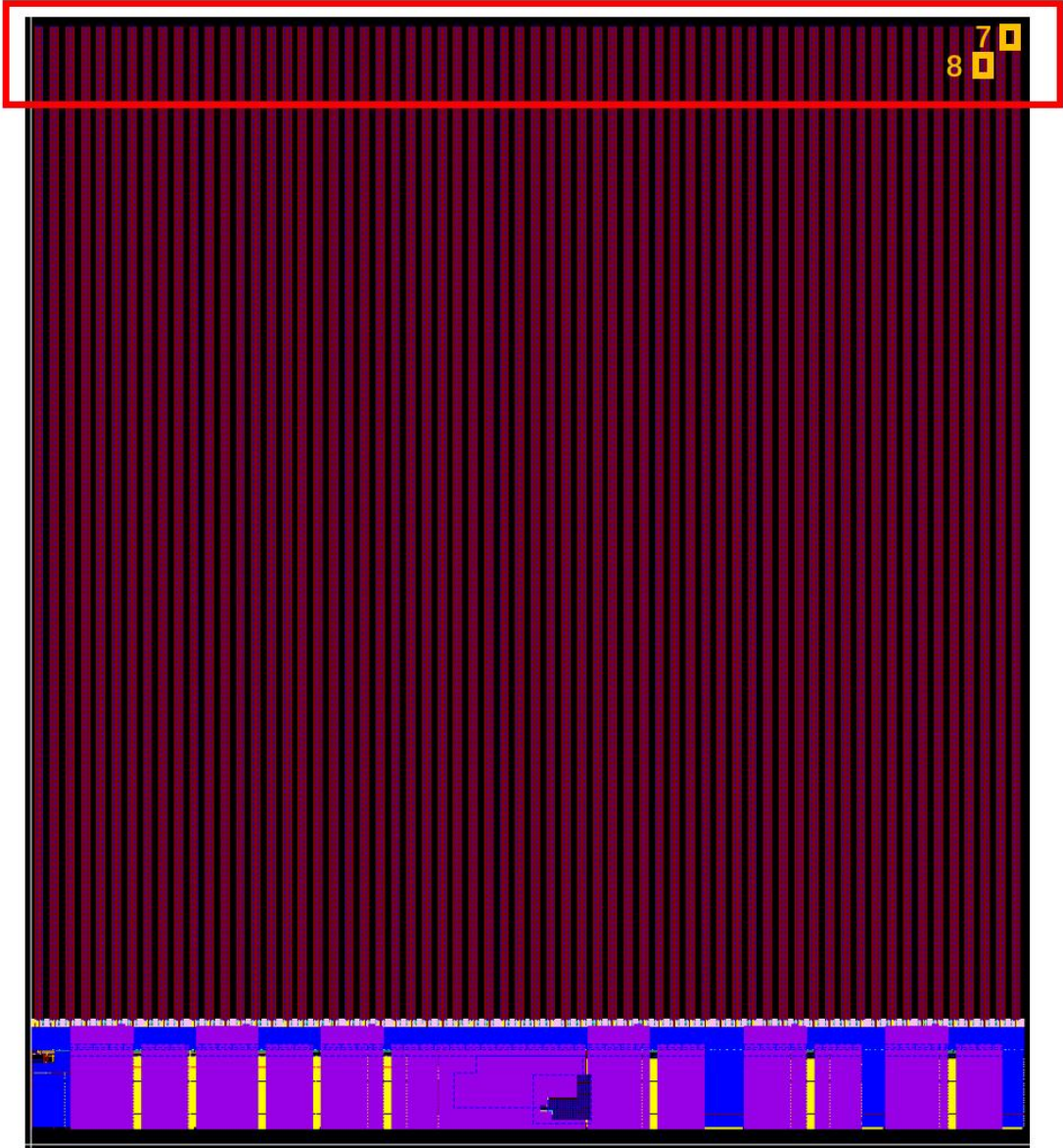


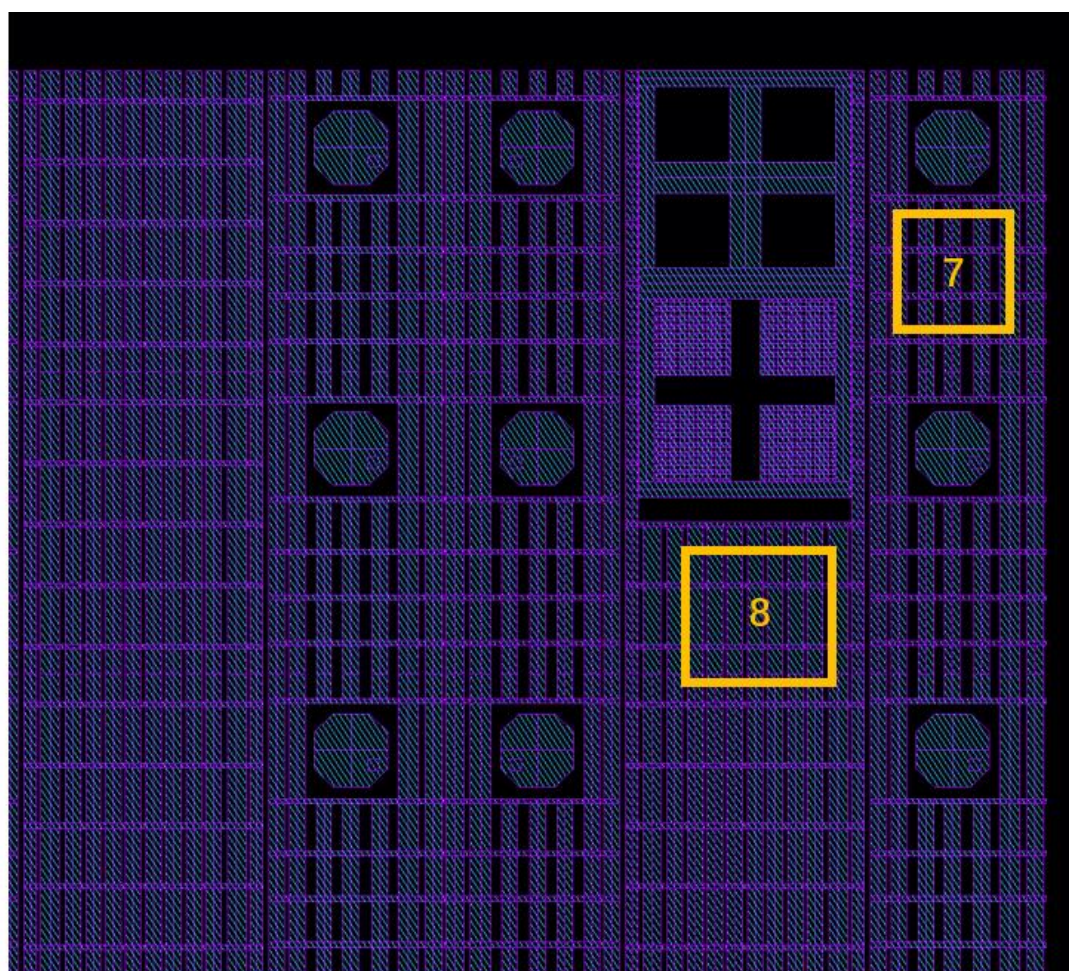
3) 5, 6 号点位





4) 7, 8 号点位





5) 9, 10 号点位

